TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

# 2SK2544

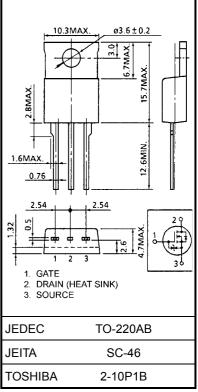
### **Switching Regulator Applications**

Unit: mm

 $\begin{array}{ll} \bullet & Low\ drain-source\ ON\ resistance & \vdots\ R_{DS}\ (ON) = 0.9\ \Omega(typ.) \\ \bullet & High\ forward\ transfer\ admittance & \vdots\ |\ Y_{fs}\ | = 5.5\ S\ (typ.) \\ \bullet & Low\ leakage\ current & \vdots\ I_{DSS} = 100\ \mu A\ (max)\ (V_{DS} = 600\ V) \\ \bullet & Enhancement-mode & \vdots\ V_{th} = 2.0 \sim 4.0\ V\ (V_{DS} = 10\ V,\ I_{D} = 1\ mA) \\ \end{array}$ 

#### **Maximum Ratings (Ta = 25°C)**

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	600	V	
Drain-gate voltage (Ro	<sub>SS</sub> = 20 kΩ)	$V_{DGR}$	600	V	
Gate-source voltage		$V_{GSS}$	±30	V	
Drain current	DC (Note 1)	I <sub>D</sub>	6	Α	
	Pulse (Note 1)	I <sub>DP</sub>	24	Α	
Drain power dissipation	n (Tc = 25°C)	$P_{D}$	80	W	
Single pulse avalanche	e energy (Note 2)	E <sub>AS</sub>	345	mJ	
Avalanche current		I <sub>AR</sub>	6	Α	
Repetitive avalanche e	nergy (Note 3)	E <sub>AR</sub>	8	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature ra	ange	T <sub>stg</sub>	-55~150	°C	



Weight: 2.0 g (typ.)

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	1.56	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	83.3	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

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Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C (initial), L = 16.8 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 6 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device.

Please handle with caution.

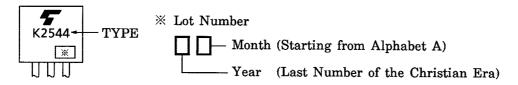
## **Electrical Characteristics (Ta = 25°C)**

Charac	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±25 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Gate-source bre	eakdown voltage	V (BR) GSS	$I_{G} = \pm 10 \ \mu A, \ V_{GS} = 0 \ V$	±30	_	_	V
Drain cut-off cu	rrent	I <sub>DSS</sub>	V <sub>DS</sub> = 600 V, V <sub>DS</sub> = 0 V	-	_	100	μΑ
Drain-source br	eakdown voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	600	_	_	V
Gate threshold v	/oltage	$V_{th}$	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3 A	_	0.9	1.25	Ω
Forward transfer	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 3 A	2.0	5.5	_	S
Input capacitano	ce	C <sub>iss</sub>		_	1300	_	
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	130	_	pF
Output capacitance		Coss		_	400	_	
Switching time	Rise time	t <sub>r</sub>	$V_{GS}$ $V_{OV}$ $V_{OU}$ $V_{OU}$ $V_{OU}$ $V_{OU}$ $V_{OU}$ $V_{OU}$ $V_{OU}$ $V_{OU}$	_	25	_	
	Turn-on time	t <sub>on</sub>			45	ı	ne
	Fall time	t <sub>f</sub>		1	40	1	ns
	Turn-off time	t <sub>off</sub>	Duty $\leq 1\%$ , $t_{\rm W} = 10 \mu \rm s$	-	150		
Total gate charge (Gate-source plus gate-drain)		Qg	V <sub>DD</sub> ≈ 400 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6 A		30		nC
Gate-source charge		Q <sub>gs</sub>		_	18	_	
Gate-drain ("mil	ller") charge	$Q_{gd}$	]		12	_	

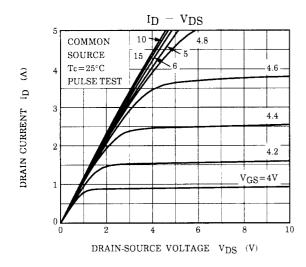
### **Source-Drain Ratings and Characteristics (Ta = 25°C)**

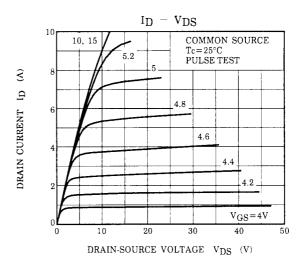
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>		_	_	6	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>		_	-	24	Α
Forward voltage (diode)	$V_{DSF}$	I <sub>DR</sub> = 6 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 6 A, V <sub>GS</sub> = 0 V		1000	_	ns
Reverse recovery charge	$Q_{rr}$	dI <sub>DR</sub> / dt = 100 A / μs	_	7	_	μC

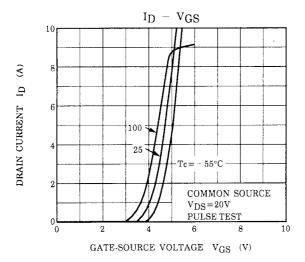
# Marking

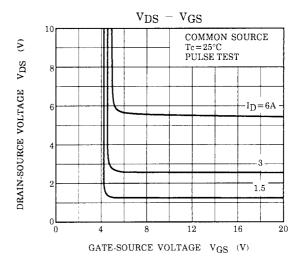


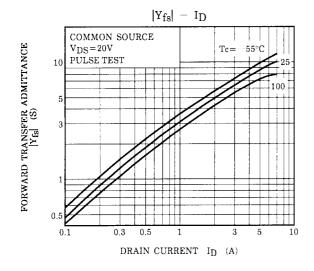
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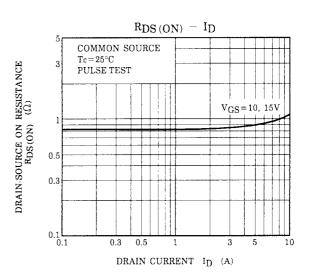




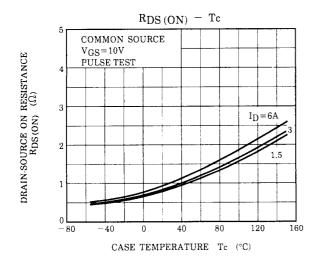


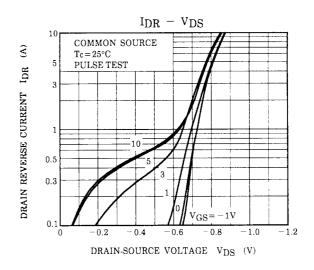


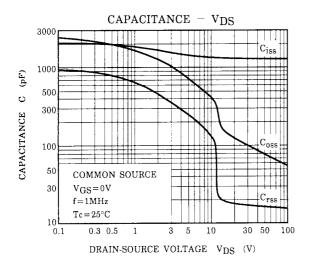


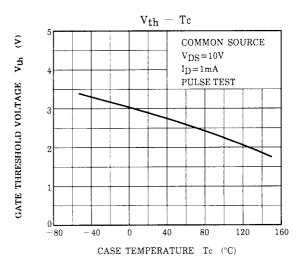


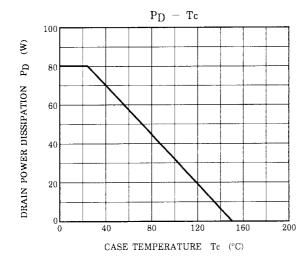
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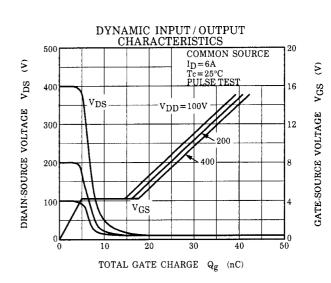




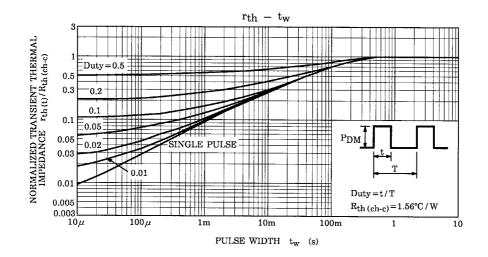


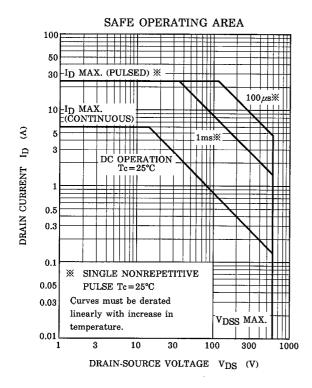


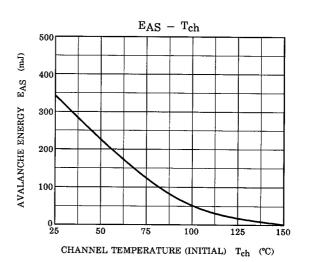


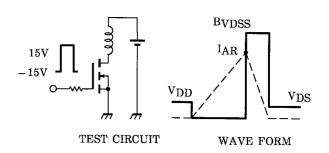


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$$\begin{aligned} &RG = 25 \ \Omega \\ &V_{DD} = 90 \ V, \ L = 16.8 \ mH \end{aligned} \qquad EAS = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{BVDSS}{BVDSS - VDD} \right)$$

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